

TinyLogic HST 2-Input NAND Gate

NC7ST00

Description

The NC7ST00 is a single 2–Input high performance CMOS NAND Gate, with TTL–compatible inputs. Advanced Silicon Gate CMOS fabrication assures high speed and low power circuit operation. ESD protection diodes inherently guard both inputs and output with respect to the V_{CC} and GND rails. High gain circuitry offers high noise immunity and reduced sensitivity to input edge rate. The TTL–compatible inputs facilitate TTL to NMOS / CMOS interfacing. Device performance is similar to MM74HCT but with 1/2 the output current drive of HC / HCT.

Features

- Space Saving SOT23-5, SC-74A and SC-88A 5-Lead Package
- Ultra Small MicroPak™ Leadless Package
- High Speed: $t_{PD} < 7$ ns Typ, $V_{CC} = 5$ V, $C_L = 15$ pF
- Low Quiescent Power: $I_{CC} < 1 \mu A$ Typ, $V_{CC} = 5.5 \text{ V}$
- Balanced Output Drive: 2 mA I_{OL}, -2 mA I_{OH}
- TTL-compatible Inputs
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

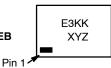


Figure 1. Logic Symbol

MARKING DIAGRAMS



SIP6 CASE 127EB





SC-74A CASE 318BQ





SOT23-5 CASE 527AH





SC-88A CASE 419A-02



E3, 8S00, T00 = Specific Device Code

KK = 2-Digit Lot Run Traceability Code

XY = 2-Digit Date Code FormatZ = Assembly Plant Code

M = Date Code

■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 4 of this data sheet.

NC7ST00

Pin Configurations

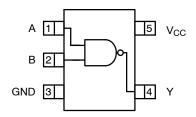


Figure 2. SOT23-5, SC-88A and SC-74A (Top View)

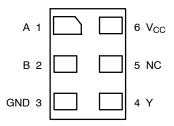


Figure 3. MicroPak (Top Through View)

PIN DESCRIPTIONS

Pin Names	Description
A, B	Inputs
Y	Output
NC	No Connect

FUNCTION TABLE $(Y = \overline{AB})$

Inp	Output	
Α	В	Υ
L	L	Н
L	Н	Н
Н	L	Н
Н	Н	L

H = HIGH Logic Level L = LOW Logic Level

ABSOLUTE MAXIMUM RATINGS

Symbol	Paramete	r	Min	Max	Unit
V _{CC}	Supply Voltage	upply Voltage		6.5	V
I _{IK}	DC Input Diode Current	V _{IN} < 0 V	-	-20	mA
		V _{IN} > V _{CC}	-	+20	
V _{IN}	DC Input Voltage		-0.5	V _{CC} + 0.5	V
l _{ok}	DC Output Diode Current V _{OUT} < 0 V		-	-20	mA
		V _{OUT} > V _{CC}	-	+20	
V _{OUT}	Output Voltage		-0.5	V _{CC} + 0.5	V
l _{out}	DC Output Source or Sink Current		-	±12.5	mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current per Supply Pin		-	±25	mA
T _{STG}	Storage Temperature		-65	+150	°C
TJ	Junction Temperature		-	+150	°C
TL	Lead Temperature (Soldering, 10 Seconds)		-	+260	°C
P_{D}	Power Dissipation in Still Air	SC-74A / SOT23-5	-	390	mW
		SC-88A	-	332	
		MicroPak-6	-	812	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

NC7ST00

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	Supply Voltage		4.5	5.5	V
V _{IN}	Input Voltage		0	V _{CC}	V
V _{OUT}	Output Voltage		0	V _{CC}	V
T _A	Operating Temperature		-40	+85	°C
t _r , t _f	Input Rise and Fall Time	V _{CC} = 5.0 V	0	10	ns/V
θ_{JA}	Thermal Resistance	SC-74A / SOT23-5	-	320	°C/W
		SC-88A	-	377	
		MicroPak-6	-	154	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTICAL CHARACTERISTICS

				-	Γ _A = +25°C	;	T _A = -40	to +85°C	
Symbol	Parameter	V _{CC} (V)	Conditions	Min	Тур	Max	Min	Max	Unit
V _{IH}	HIGH Level Input Voltage	4.5 – 5.5		2.0	-	-	2.0	-	V
V _{IL}	LOW Level Input Voltage	4.5 – 5.5		-	_	0.8	_	0.8	V
V _{OH}	HIGH Level Output Voltage	4.5 4.5	$\begin{split} I_{OH} &= -20 \ \mu\text{A} \\ I_{OH} &= -2 \ \text{mA} \\ V_{IN} &= V_{IH} \ \text{or} \ V_{IL} \end{split}$	4.4 4.18	4.5 4.35	-	4.4 4.13	-	V
V _{OL}	LOW Level Output Voltage	4.5 4.5	$\begin{split} I_{OL} &= 20 \; \mu\text{A} \\ I_{OL} &= 2 \; \text{mA} \\ V_{IN} &= V_{IH} \; \text{or} \; V_{IL} \end{split}$	-	0 0.10	0.1 0.26	-	0.1 0.33	٧
I _{IN}	Input Leakage Current	5.5	$0 \leq V_{IN} \leq 5.5 \text{ V}$	-	-	±0.1	_	±1.0	μΑ
Icc	Quiescent Supply Current	5.5	V _{IN} = V _{CC} or GND	-	_	1.0	_	10.0	μΑ
I _{CCT}	I _{CC} per Input	5.5	One Input V_{IN} = 0.5 V or 2.4 V, Other Input V_{CC} or GND	. 1	ı	2.0	-	2.9	mA

AC ELECTRICAL CHARACTERISTICS

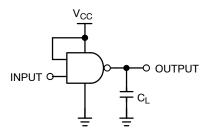
					T _A = +25°($T_A = -40$	to +85°C	
Symbol	Parameter	V _{CC} (V)	Conditions	Min	Тур	Max	Min	Max	Unit
t _{PLH} , t _{PHL}	Propagation Delay (Figure 4, 6)	5.0	C _L = 15 pF	_	3.4	12	-	_	ns
				_	6.3	17	-	_	
		4.5	C _L = 50 pF	-	6.0	16	-	20	
				-	11.5	27	-	31	
		5.5		-	4.1	14	-	18	
				-	11.2	26	-	30	
t _{TLH} , t _{THL}		5.0	C _L = 15 pF	-	4	10	-	-	ns
	(Figure 4, 6)	4.5	C _L = 50 pF	_	11	25	-	31	
		5.5		-	10	21	-	26	
C _{IN}	Input Capacitance	Open		_	2	10	-	-	pF
C_{PD}	Power Dissipation Capacitance (Figure 5)	5.0	(Note 2)	_	6	_	-	_	pF

^{2.} C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current. Current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. (See Figure 5). C_{PD} is related to I_{CCD} dynamic operating current by the expression: I_{CCD} = (C_{PD}) (V_{CC}) (f_{IN}) + (I_{CCstatic}).

^{1.} Unused inputs must be held HIGH or LOW. They may not float.

NC7ST00

AC Loading and Waveforms



 C_L includes load and stray capacitance Input PRR = 1.0 MHz, $t_W = 500 \ \text{ns}$

Figure 4. AC Test Circuit

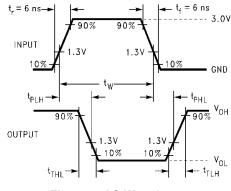
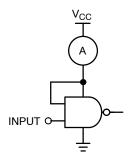


Figure 6. AC Waveforms



Input = AC Waveform;

PRR = Variable; Duty Cycle = 50%.

Figure 5. I_{CCD} Test Circuit

ORDERING INFORMATION

Device	Top Mark	Packages	Shipping [†]
NC7ST00M5X	8S00	SC-74A	3000 / Tape & Reel
NC7ST00M5X-L22090	8S00	SOT23-5	3000 / Tape & Reel
NC7ST00P5X	T00	SC-88A	3000 / Tape & Reel
NC7ST00P5X-L22057	T00	SC-88A	3000 / Tape & Reel
NC7ST00L6X	E3	SIP6, MicroPak	5000 / Tape & Reel
NC7ST00L6X-L22175	E3	SIP6, MicroPak	5000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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DATE 31 AUG 2016



NOTES:

- 1. CONFORMS TO JEDEC STANDARD MO-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-2009
 4. PIN ONE IDENTIFIER IS 2X LENGTH OF ANY

 - OTHER LINE IN THE MARK CODE LAYOUT.

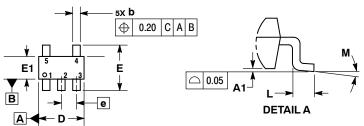
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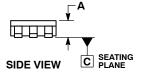
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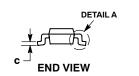


DATE 18 JAN 2018





TOP VIEW

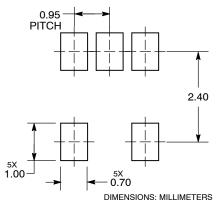


NOTES:

- IES:
 DIMENSIONING AND TOLERANCING PER ASME
 Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH
 THICKNESS. MINIMUM LEAD THICKNESS IS THE
 MINIMUM THICKNESS OF BASE MATERIAL.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.

	MILLIN	IETERS	
DIM	MIN	MAX	
Α	0.90	1.10	
A1	0.01	0.10	
b	0.25	0.50	
С	0.10	0.26	
D	2.85	3.15	
E	2.50	3.00	
E1	1.35	1.65	
е	0.95 BSC		
L	0.20	0.60	
м	0 °	10°	

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

Μ = Date Code = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	SC-74A		PAGE 1 OF 1

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SC-88A (SC-70-5/SOT-353) CASE 419A-02 ISSUE M

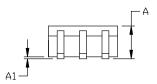
DATE 11 APR 2023

NOTES:

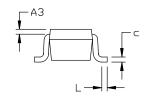
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETERS
- 419A-01 DBSDLETE. NEW STANDARD 419A-02
- DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.1016MM PER SIDE.

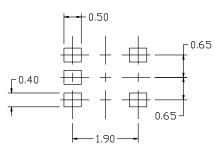
DIM	MI	MILLIMETERS				
ויודת	MIN.	N□M.	MAX.			
А	0.80	0.95	1.10			
A1			0.10			
A3	0.20 REF					
b	0.10	0.20	0.30			
C	0.10		0.25			
D	1.80	2.00	2,20			
Е	2.00	2.10	2.20			
E1	1.15	1.25	1.35			
е		0.65 BSI				
L	0.10	0.15	0.30			

e Ε1 0 5X b



◆ 0.2 M B M





RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

XXX = Specific Device Code

= Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

STYLE 1:
PIN 1. BASE
EMITTER
3. BASE
COLLECTOR
COLLECTOR

3. EMITTER 1

4. COLLECTOR

STYLE 2: PIN 1. ANODE 2. EMITTER 3. BASE 4. COLLECTOR CATHODE

3. BASE

4. COLLECTOR

STYLE 3: PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. CATHODE 1

4. BASE

5. EMITTER

STYLE 4: PIN 1. SOURCE 1 2. DRAIN 1/2 3 SOURCE 1 4. GATE 1 5. GATE 2

3. ANODE 4. ANODE

ANODE
 ANODE

STYLE 5: PIN 1. CATHODE 2. COMMON ANODE 3. CATHODE 2 4. CATHODE 3 5. CATHODE 4

out in the datasheet refer to the device

datasheet pinout or pin assignment.

STYLE 6: STYLE 7: STYLE 8: STYLE 9: Note: Please refer to datasheet for PIN 1. EMITTER 2 PIN 1. CATHODE 2. COLLECTOR 3. N/C PIN 1. ANODE 2. CATHODE PIN 1. BASE style callout. If style type is not called 2. EMITTER 2. BASE 2

5. COLLECTOR 2/BASE 1 5. COLLECTOR **DOCUMENT NUMBER:** 98ASB42984B

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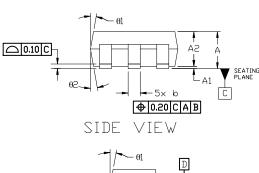




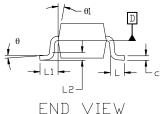
В

F1 F

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 19894
- CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE
- DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS, MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.25 PER SIDE. D AND E1 DIMENSIONS ARE DETERMINED AT DATUM D.
- DIMENSION 'b' DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL BE O. 08mm TOTAL IN EXCESS OF THE 'b' DIMENSION AT MAXIMUM MATERIAL CONDITION. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD SHALL NOT BE LESS THAN 0.07mm.



TOP VIEW



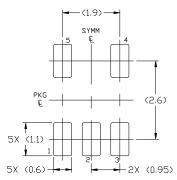
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	MILLIMETERS			
DIM	MIN.	N□M.	MAX.	
Α	0.90	_	1.45	
A1	0.00	_	0.15	
A2	0.90	1.15	1.30	
b	0.30	_	0.50	
С	0.08	_	0.22	
D	2.90 BSC			
Ε	2.80 BSC			
E1	1.60 BSC			
е	0.95 BSC			
L	0.30	0.45	0.60	
L1	0.60 REF			
L2	0.25 REF			
θ	0°	4°	8*	
θ1	0°	10°	15°	
θ2	0°	10°	15°	



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